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What is Claimed is:

1. A method of removing an optical device contained within a device package from a circuit board, wherein the device package is secured to the circuit board using an adhesive pad, the method comprising:

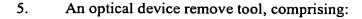
peeling a portion of the adhesive pad away from the circuit board;
inserting an optical removal tool between the optical device and the circuit
board, wherein the optical removal tool has a pair of fork portions and a cavity
positioned between the fork portion, and the fork portions straddle one or more leads
on the optical device during the inserting step; and

prying the remainder of the adhesive pad away from the circuit board using said optical device removal tool.

- 2. The method of claim 1, wherein said optical device further includes electric lead interconnects soldered to electric connections on the circuit board, the method further comprising breaking the soldered connections.
- 3. The method of claim 2, wherein the breaking the soldered connections is performed by heating the soldered connections to a temperature above a temperature at which the solder of the soldered connections melt, but below a temperature that is likely to do any thermal damage to the optical device.
- 4. The method of claim 1, further comprising: removing the adhesive pad from the device package.

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a peeling blade, the peeling blade including a plurality of fork portions, at least one cavity extending between two ones of the plurality of fork portions; and

- a handle extending substantially perpendicular to the peeling blade, wherein the cavity extends into the handle.
 - 6. The optical device removal tool of claim 5, wherein the plurality of fork portions are configured to fit under an overhang separating an optical device from a circuit board.
 - 7. The optical device removal tool of claim 5, wherein electrical leads from an optical device fit within the cavity during normal operation of the optical device removal tool.